

Manual Update Sheet

TMS320VC5501/VC5502 MicroStar BGA Discontinued and Redesigned



ABSTRACT

This document should be used in conjunction with the device data sheet and describes the updated package designator for the indicated devices.

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Trademarks

MicroStar BGA™ and MicroStar Junior™ are trademarks of Texas Instruments.
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1 Package Redesign Details

Explanation

The devices in the MicroStar BGA™ packaging were redesigned using a laminate nfBGA package. This nfBGA package offers datasheet-equivalent electrical performance. It is also footprint equivalent to the MicroStar BGA. For more details, please refer to this [nfBGA Packaging Application Report](#).

When referencing the device data sheet, use the new package designator in place of the discontinued package designator throughout the document.

The orderable addendum at the end of the device data sheet will reflect the new package designator.

See the following page or the end of the device data sheet for the updated nfBGA package drawing.

Table 1-1. Package Designator

Old Package Designator	New Package Designator
ZZZ	ZAV
GZZ	GBE

Reason for Discontinuance

Due to an equipment End-Of-Life notice from our substrate supplier, we are phasing out certain MicroStar BGA and MicroStar Junior™ BGA packaging devices and offering a Last Time Buy.

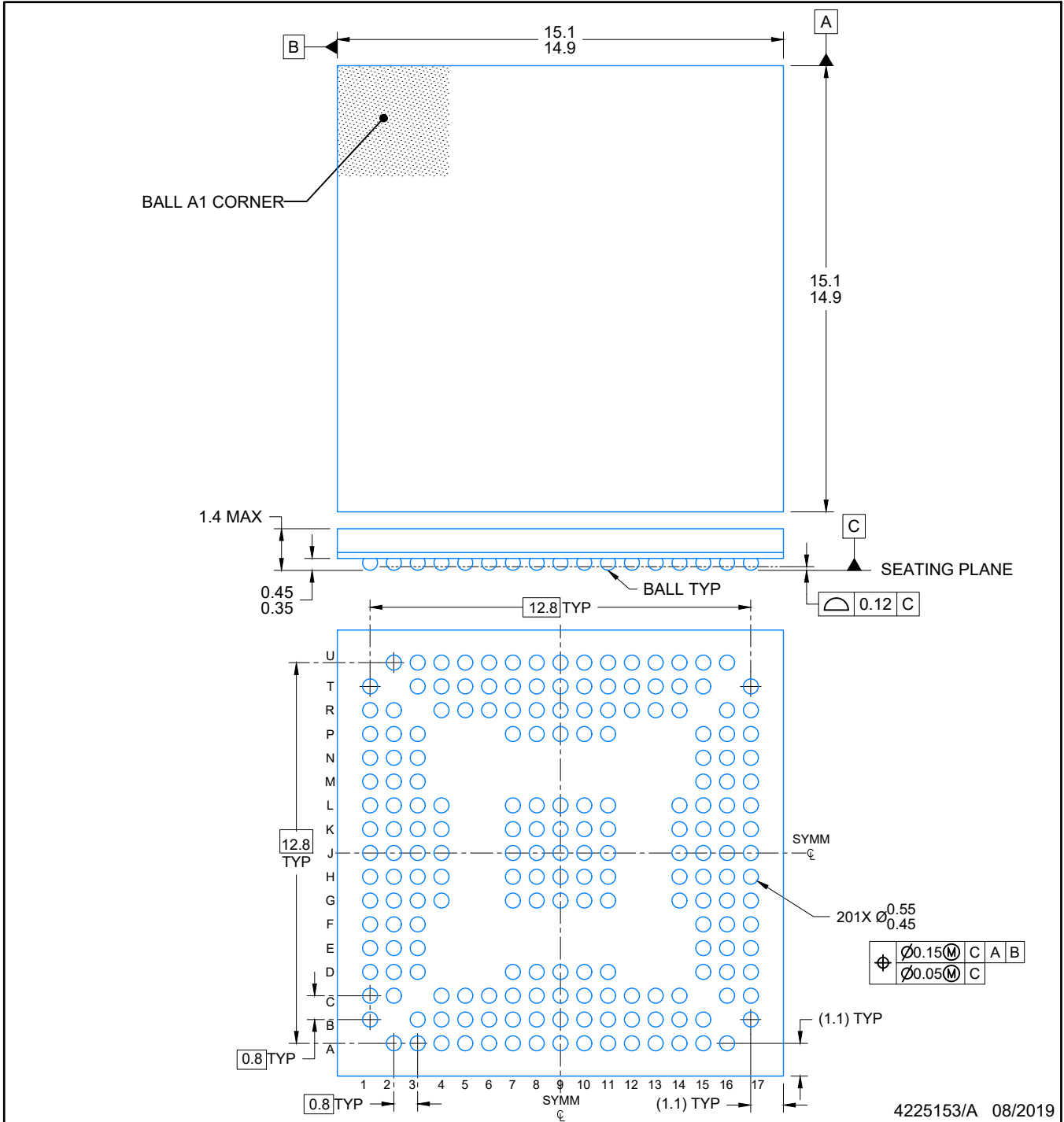
These devices have now been converted to an nfBGA package.

Devices Affected

The following table describes the devices affected, the old and new package designators, and references to the device data sheet.

Table 1-2. Devices and Nomenclature

Device	Discontinued MicroStar BGA Device	Redesigned Laminate nfBGA Device	Device Data Sheet
TMS320VC5501	TMS320VC5501ZZZ300	TMS320VC5501ZAV300	SPRS206
TMS320VC5501	TMS320VC5501GZZ300	TMS320VC5501GBE300	SPRS206
TMS320VC5502	TMS320C5502ZZZR300	TMS320C5502ZAVR300	SPRS166
TMS320VC5502	TMS320VC5502GZZ200	TMS320VC5502GBE200	SPRS166
TMS320VC5502	TMS320VC5502GZZ300	TMS320VC5502GBE300	SPRS166
TMS320VC5502	TMS320VC5502ZZZ200	TMS320VC5502ZAV200	SPRS166
TMS320VC5502	TMS320VC5502ZZZ300	TMS320VC5502ZAV300	SPRS166

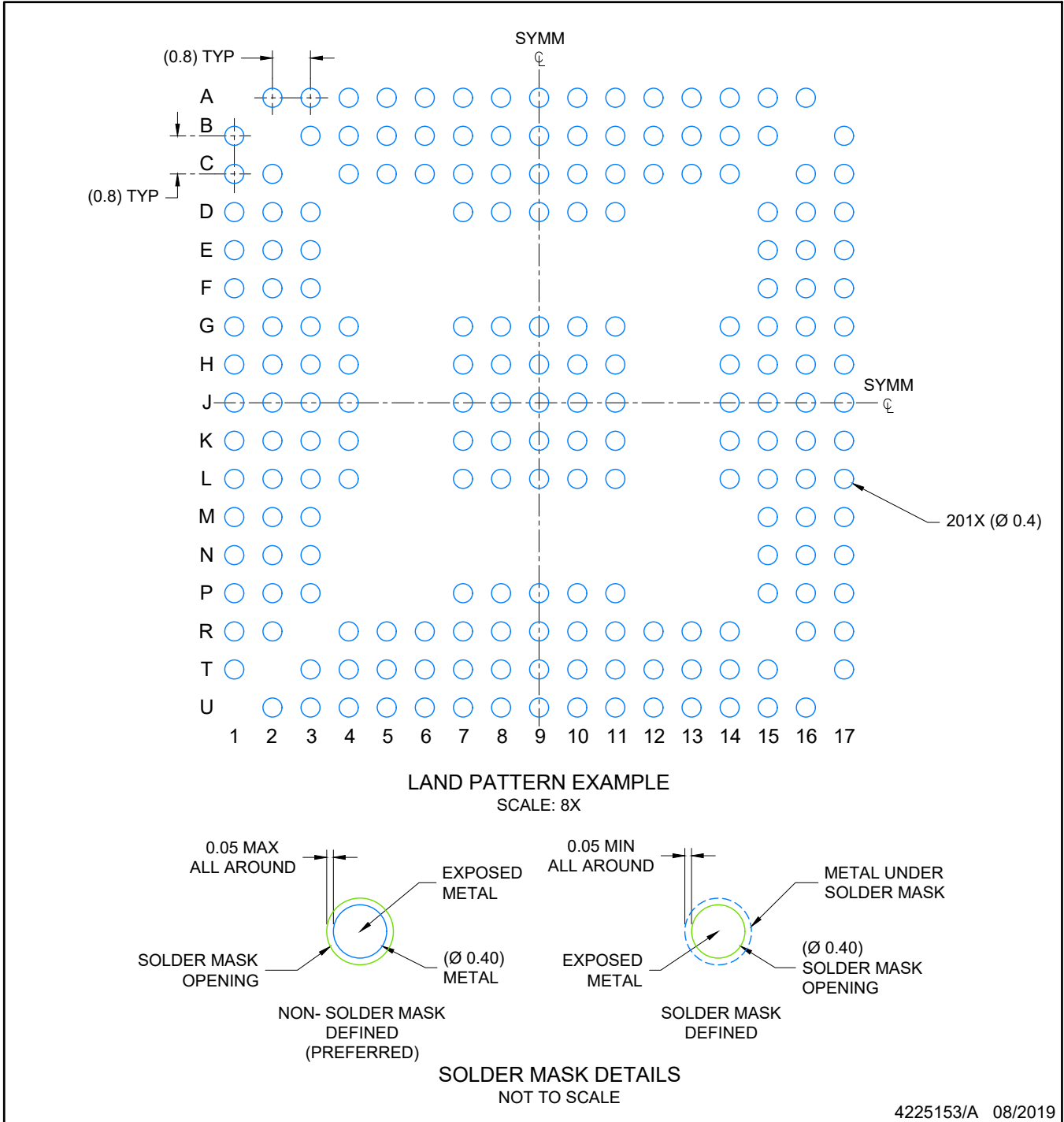


4225153/A 08/2019

NOTES:

NanoFree is a trademark of Texas Instruments.

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.



NOTES: (continued)

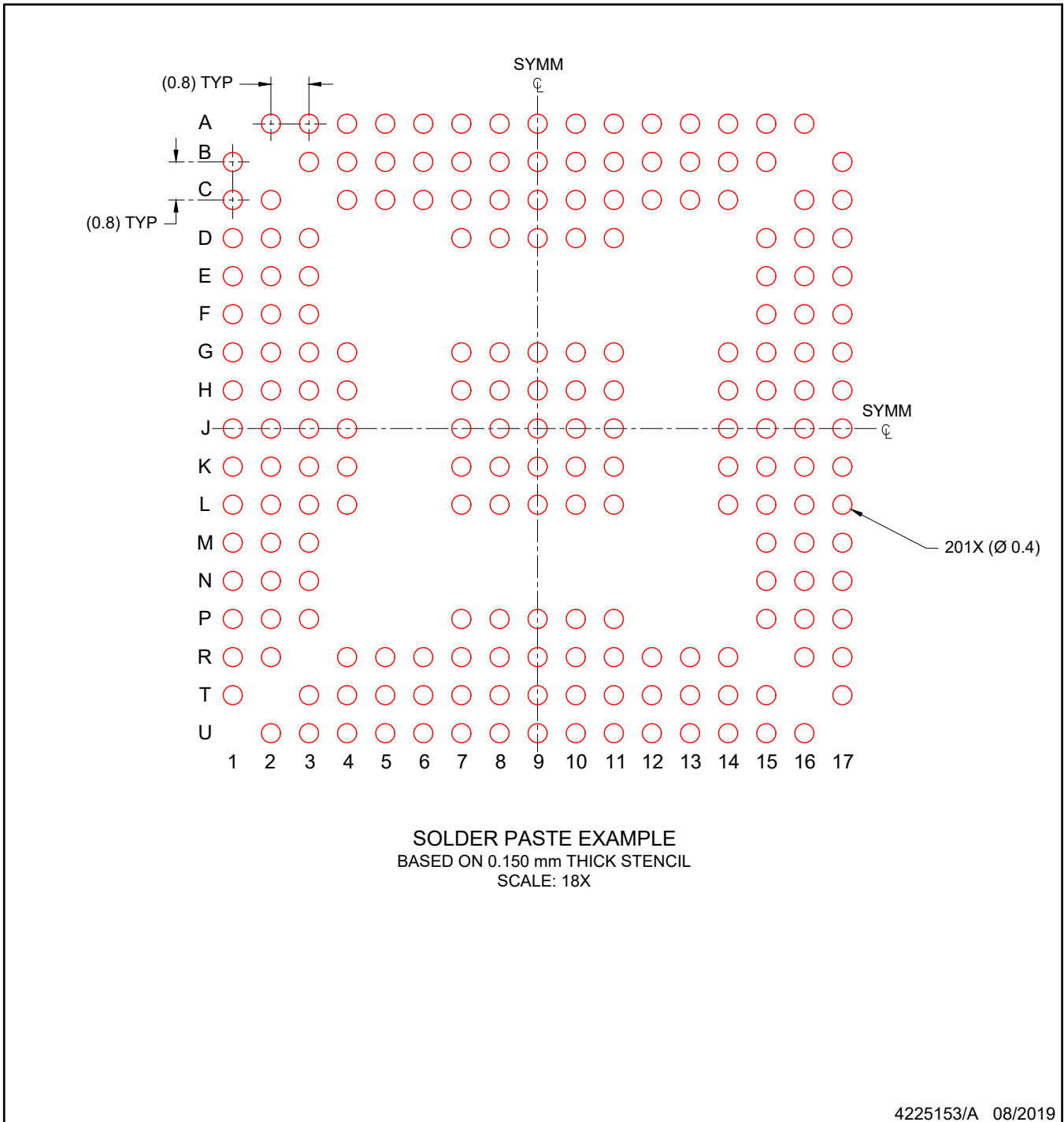
- Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. Refer to Texas Instruments Literature number SNVA009 (www.ti.com/lit/snva009).

EXAMPLE STENCIL DESIGN

ZAV0201A

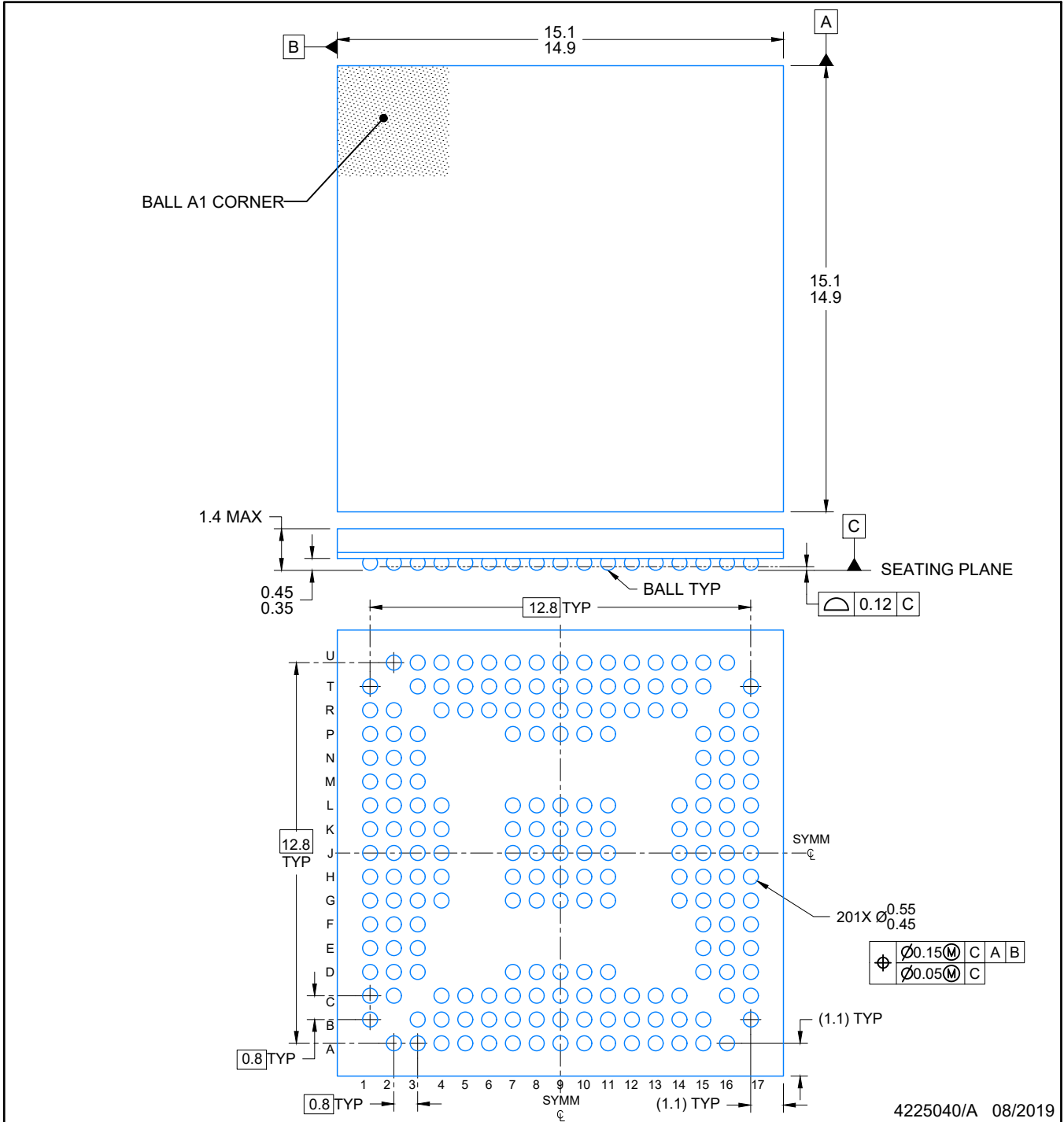
NFBGA - 1.4 mm max height

PLASTIC BALL GRID ARRAY



NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

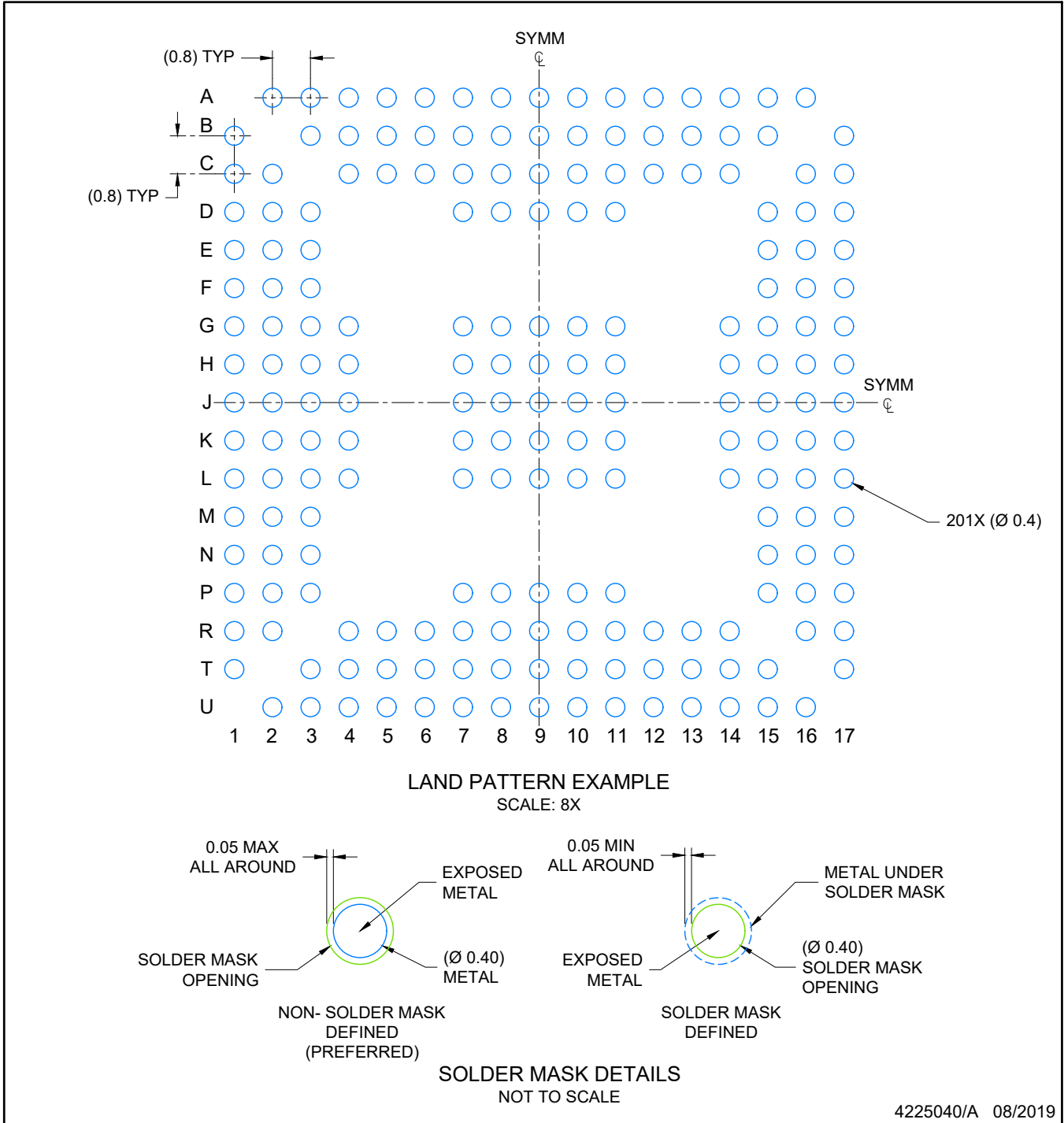


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2. This drawing is subject to change without notice.



NOTES: (continued)

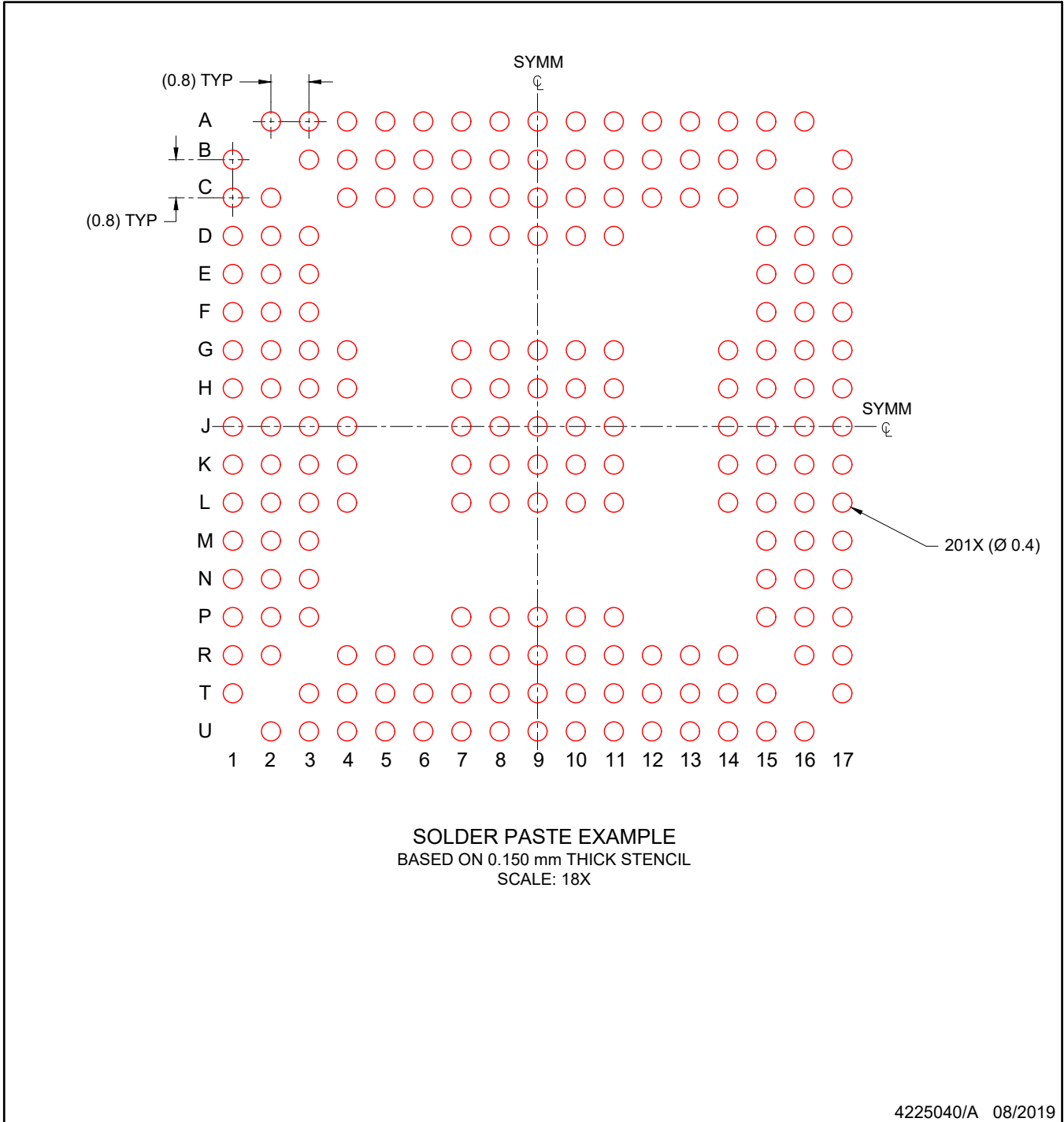
- Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. Refer to Texas Instruments Literature number SNVA009 (www.ti.com/lit/snva009).

EXAMPLE STENCIL DESIGN

GBE0201A

NFBGA - 1.4 mm max height

PLASTIC BALL GRID ARRAY



NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

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